

WHAT IS CLAIMED IS:

1. An apparatus comprising:  
an integrated circuit die;  
an integrated circuit package coupled to a first face of the integrated circuit die;  
5 mold compound in contact with the integrated circuit die and the integrated circuit package; and  
an overlayer coupled to the mold compound and to a second face of the integrated circuit die.
- 10 2. An apparatus according to Claim 1, further comprising:  
underfill material disposed between the integrated circuit die and the integrated circuit package.
- 15 3. An apparatus according to Claim 1, wherein the overlayer comprises thermally conductive material.
4. An apparatus according to Claim 1, wherein the overlayer comprises cured die attach film.
- 20 5. An apparatus according to Claim 1, wherein the overlayer comprises cured die attach paste.
6. An apparatus comprising:  
an integrated circuit package substrate;

a plurality of integrated circuit die, a first face of each of the plurality of integrated circuit die attached to the integrated circuit package substrate; and

mold compound in contact with the plurality of integrated circuit die and the integrated circuit package substrate; and

5 an overlayer coupled to the mold compound and to a second face of each of the plurality of integrated circuit die.

7. An apparatus according to Claim 6, further comprising:

underfill material disposed between the first face of each of the plurality of  
10 integrated circuit die and the integrated circuit package substrate.

8. An apparatus according to Claim 6, wherein the overlayer comprises thermally conductive material.

15 9. An apparatus according to Claim 6, wherein the overlayer comprises cured die attach film.

10. An apparatus according to Claim 6, wherein the overlayer comprises cured die attach paste.

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11. A method comprising:

placing an overlayer in contact with mold compound and a first face of an integrated circuit die,

wherein a second face of the integrated circuit die is coupled to an integrated circuit  
25 package, and

wherein the mold compound is in contact with the integrated circuit die and the integrated circuit package.

12. A method according to Claim 11, further comprising:

5        singulating one of the plurality of integrated circuit die and a respective mounting location of the integrated package substrate.

13. A method according to Claim 11, wherein the overlayer comprises thermally conductive material.

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14. A method according to Claim 11, wherein the overlayer comprises cured die attach film.

15        15. A method according to Claim 11, wherein the overlayer comprises cured die attach paste.

16. A system comprising:

a microprocessor comprising:

an integrated circuit die;

20        an integrated circuit package coupled to a first face of the integrated circuit die;

mold compound in contact with the integrated circuit die and the integrated circuit package; and

25        an overlayer coupled to the mold compound and to a second face of the integrated circuit die; and

a double data rate memory electrically coupled to the microprocessor.

17. A system according to Claim 16, wherein the overlayer comprises thermally conductive material.

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18. A system according to Claim 16, further comprising:  
a motherboard electrically coupled to the microprocessor and to the memory.